

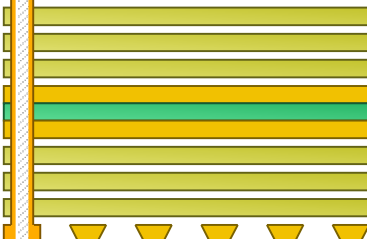
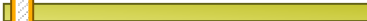




Layer	Stack up	Supplier	Supplier Description	Description	Type	Base Thickness	Processed Thickness	εr	Tg	
1		Electra Polymers		Liquid PhotolImageable Mask	SolderMask			4.000		
				Copper Foil	Copper	0.018	0.038			
2		Shanghai Nanya	NY2150	Prepreg1080	Dielectric	0.070	0.070	4.200	150.000	
		Shanghai Nanya	NY2150	PrePreg 7628	Dielectric	0.187	0.186	4.200	150.000	
		Shanghai Nanya	NY2150	Prepreg1080	Dielectric	0.070	0.070	4.200	150.000	
		Shanghai Nanya	NY2150	NY2150 Core	FR4	0.035	0.035	4.200	150.000	
							2.400	2.400		
							0.035	0.035		
							0.070	0.070	4.200	150.000
3		Shanghai Nanya	NY2150	PrePreg 7628	Dielectric	0.187	0.186	4.200	150.000	
		Shanghai Nanya	NY2150	Prepreg1080	Dielectric	0.070	0.070	4.200	150.000	
4				Circuitfoil	Copper Foil	0.018	0.038			
		Electra Polymers		Liquid PhotolImageable Mask	SolderMask			4.000		

Copper Thickness = 0.146 | Dielectric Thickness = 3.051 | Solder Mask Thickness = 0.050 | Stack Up Thickness = 3.197 | Stack Up Thickness with Soldermask = 3.247 | Stack Up Cost = 29.00 |

Drill Image	1st Layer	2nd Layer	Column Position	Drill Type
	1	4	1	Mechanical PTH

Notes

StackName: Trax_suggested ML4_3.20mm	Version:	Revision:	Modification:	Date of Revision:	Editor	Page 1/1
Date: 2018/02/27	Associated Documents:					
Author: Natheer	Quote request from Fiona @ conlog					
Department: Rfq						
Site: Cape Town						